



## DESCRIPTION

The AM4812 is the N-Channel logic enhancement mode power field effect transistor which is produced using high cell density. Advanced trench technology to provide excellent  $R_{DS(ON)}$ .

This high density process is especially tailored to minimize on-state resistance.

The AM4812 is particularly suited for low voltage application, and low in-line power loss are needed in a very small outline surface mount package.

The AM4812 is available in SOP8 Package.

## FEATURES

- 30V / 7.8A,  $R_{DS(ON)} = 16m\Omega$  (typ.)@ $V_{GS} = 10V$
- 30V / 5.8A,  $R_{DS(ON)} = 22m\Omega$  (typ.)@ $V_{GS} = 4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and Maximum DC current capability
- Available in SOP8 Package

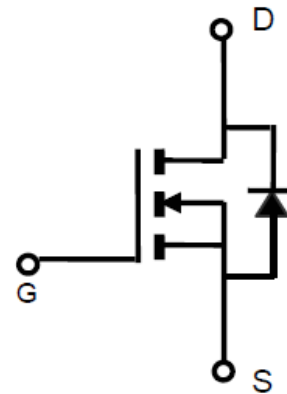
## APPLICATION

- High Frequency Point-of-Load Synchronous
- New working DC-DC Power System
- Load Switch

## ORDERING INFORMATION

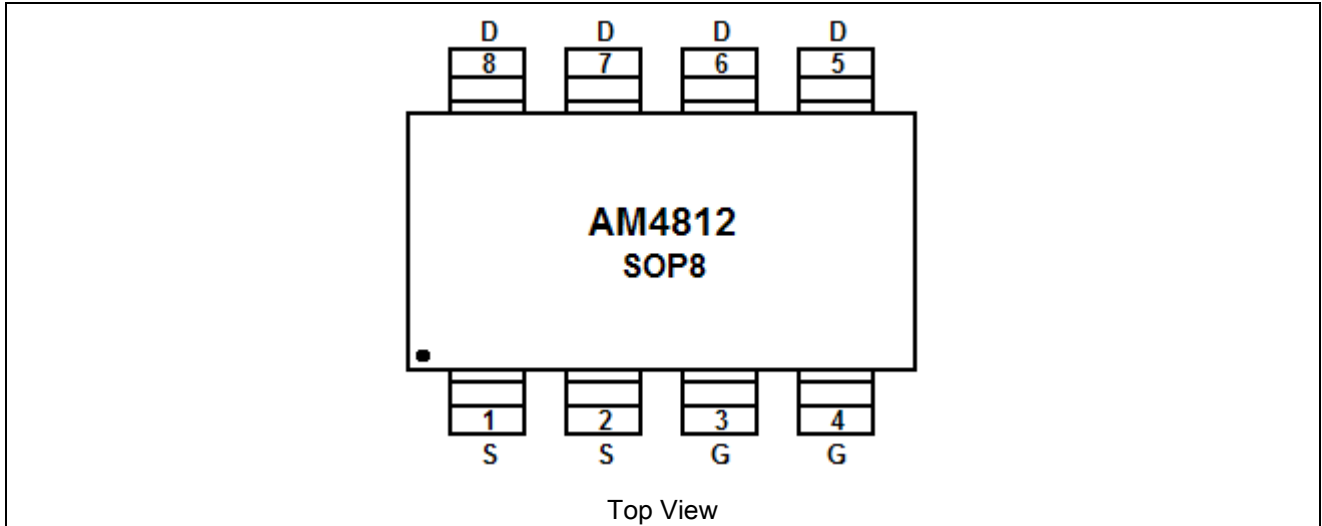
Package Type	Part Number	
SOP8	M8	AM4812M8R
		AM4812M8VR
Note	R: Tape & Reel V: Green Package	
AiT provides all Pb free products Suffix " V " means Green Package		

## N CHANNEL MOSFET





## PIN DESCRIPTION



Pin #	Symbol	Function
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain



## ABSOLUTE MAXIMUM RATINGS

T<sub>A</sub> = 25°C unless otherwise specified

V <sub>DSS</sub> , Drain-Source Voltage		30V
V <sub>GSS</sub> , Gate-Source Voltage		±20V
I <sub>D</sub> , Continuous Drain Current, V <sub>GS</sub> = 10V <sup>NOTE1</sup>	T <sub>A</sub> =25°C	10A
I <sub>DM</sub> , Pulsed Drain Current <sup>NOTE2</sup>		20A
P <sub>D</sub> , Power Dissipation	T <sub>A</sub> =25°C	3.2W
	T <sub>A</sub> =70°C	2W
T <sub>J</sub> , Operation Junction Temperature		-55°C /150°C
T <sub>STG</sub> , Storage Temperature Range		-55°C /150°C

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE1: The value of R<sub>θJA</sub> is measured with the device mounted on 1in 2 FR-4 board with 2oz.

Copper, in a still air environment with T<sub>A</sub> = 25°C.

NOTE2: The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.

## THERMAL INFORMATION

Parameter	Symbol	Typ	Unit
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	85	°C/W
Thermal Resistance-Junction to Case	R <sub>θJC</sub>	48	°C/W



## ELECTRICAL CHARACTERISTICS

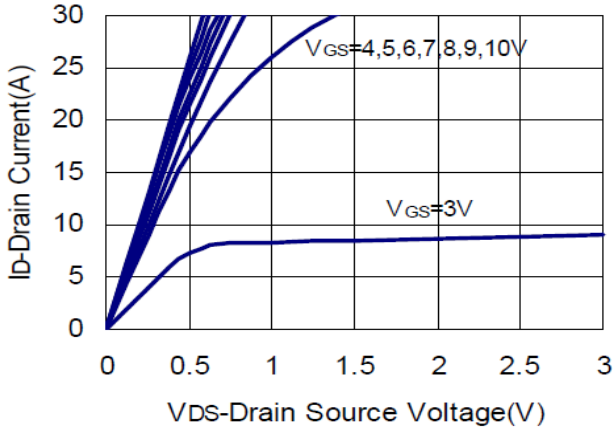
T<sub>A</sub> = 25°C unless otherwise specified

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.0	-	2.5	V
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V	-	-	1	μA
		V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V T <sub>J</sub> = 55°C	-	-	5	
On-State Drain Current	I <sub>D(ON)</sub>	V <sub>DS</sub> ≥ 5V, V <sub>GS</sub> = 10V	25	-	-	A
Drain-source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 7.8A	-	16	20	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5.8A	-	22	28	
<b>Source-Drain Diode</b>						
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 2A, V <sub>GS</sub> = 0V	-	0.8	1.2	V
<b>Dynamic Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 15V	-	7.2	-	nC
Gate-Source Charge	Q <sub>GS</sub>	V <sub>GS</sub> = 10V	-	1.6	-	
Gate-Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = 7.8A	-	2	-	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 15V V <sub>GS</sub> = 0V f = 1MHz	-	570	-	pF
Output Capacitance	C <sub>oss</sub>		-	80	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	64	-	
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 15V	-	4.2	-	nS
	t <sub>r</sub>	V <sub>GS</sub> = 10V	-	10.2	-	
Turn-Off Time	t <sub>d(off)</sub>	I <sub>D</sub> = 5A	-	16	-	
	t <sub>f</sub>	R <sub>G</sub> = 3.3Ω	-	6.2	-	

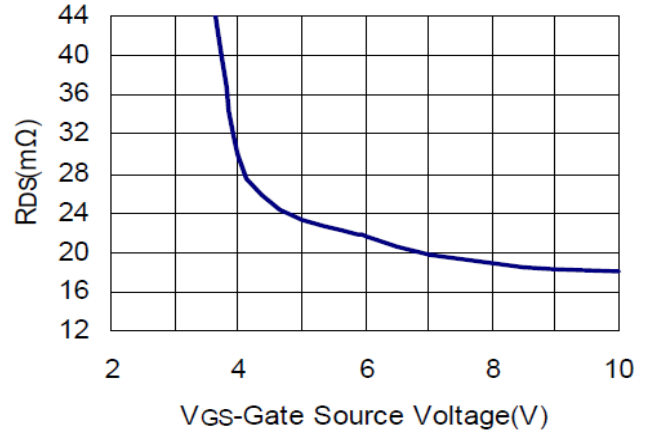


### TYPICAL CHARACTERISTICS

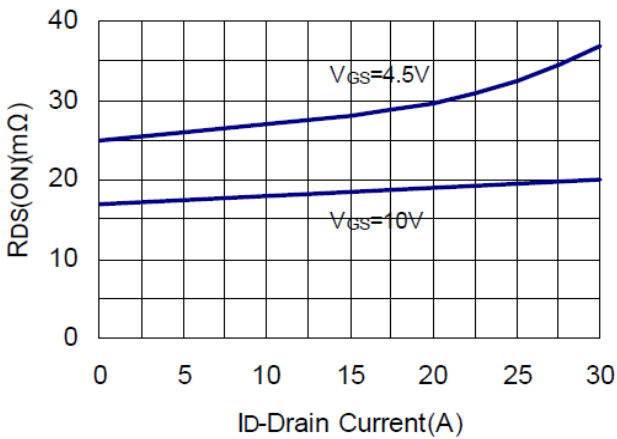
1. Output Characteristics



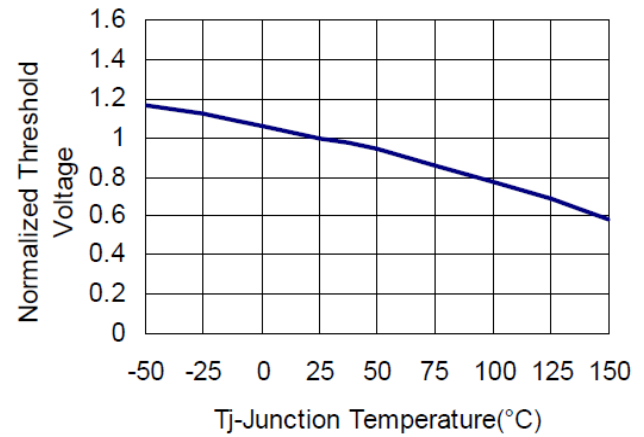
2. Drain-Source On Resistance



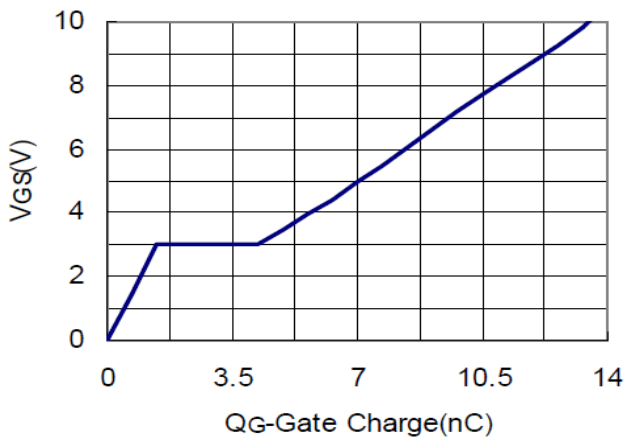
3. Drain Source On Resistance



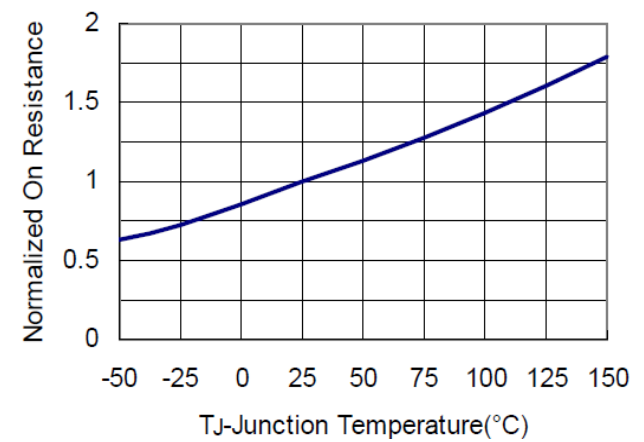
4. Gate Threshold Voltage



5. Gate Charge

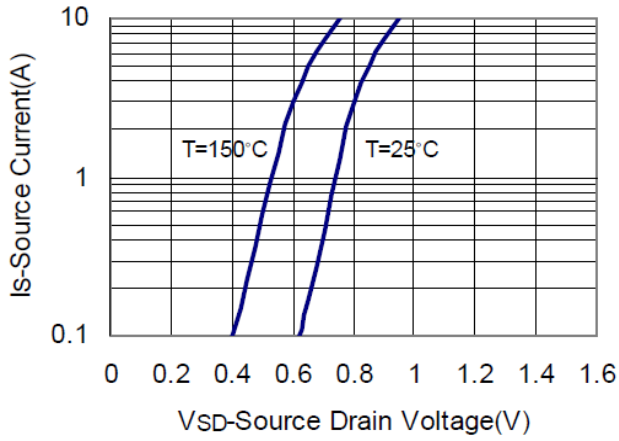


6. Drain Source On Resistance

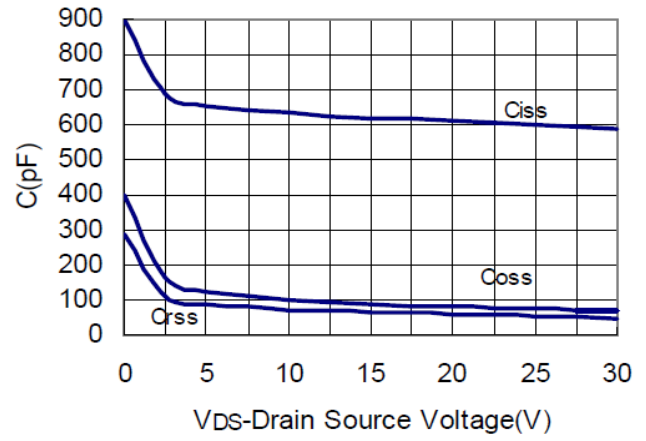




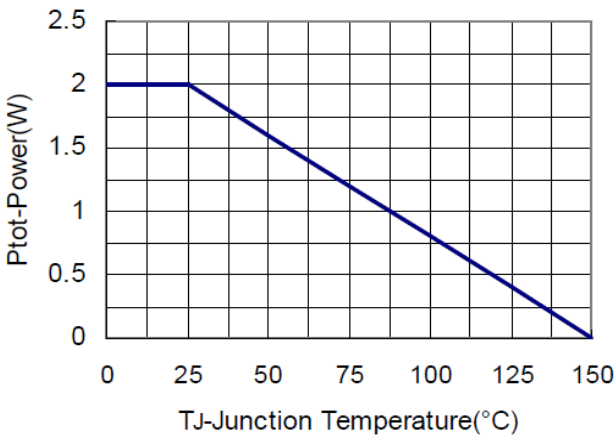
7. Source Drain Diode Forward



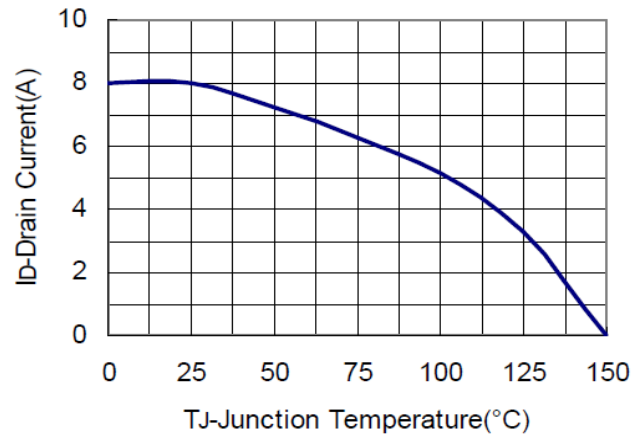
8. Capacitance



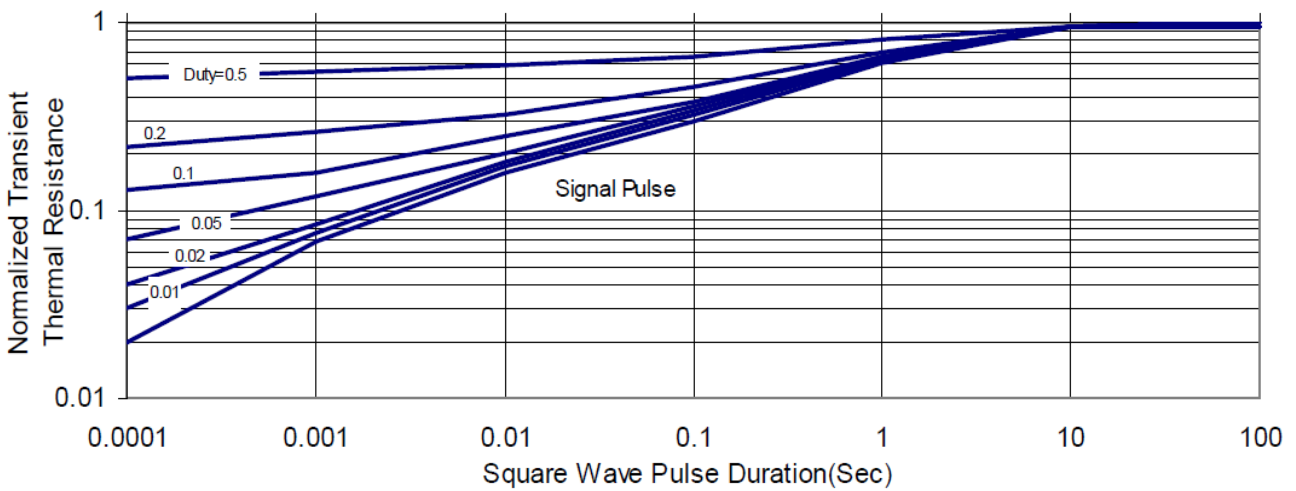
9. Power Dissipation



10. Drain Current



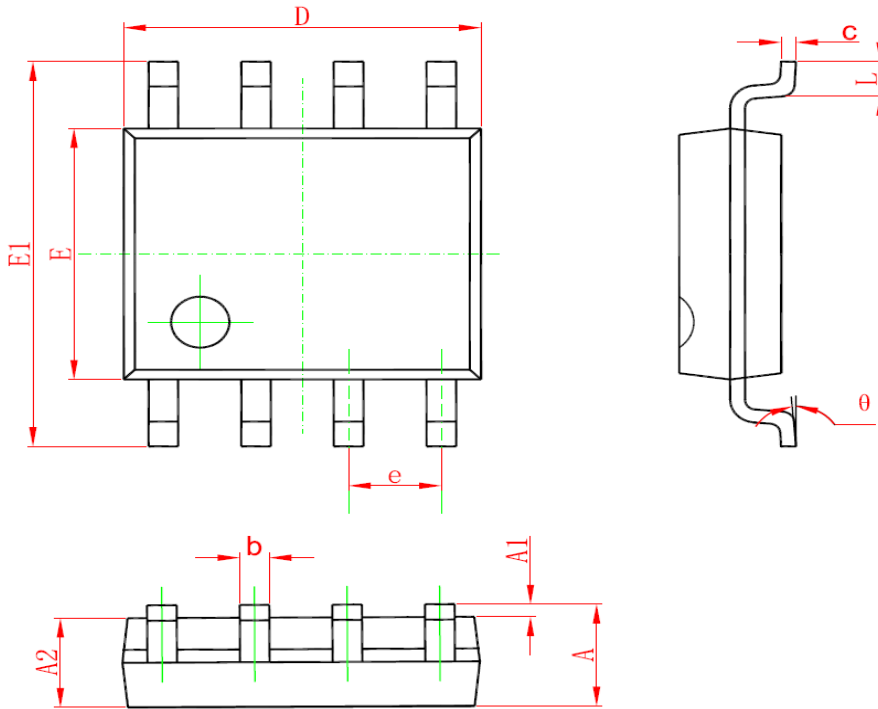
11. Thermal Transient Impedance





## PACKAGE INFORMATION

Dimension in SOP8 Package (mm)



Symbol	Min	Max
A	1.350	1.750
A1	0.100	0.250
A2	1.350	1.550
b	0.330	0.510
c	0.170	0.250
D	4.700	5.100
E	3.800	4.000
E1	5.800	6.200
e	1.270(BSC)	
L	0.400	1.270
θ	0°	8°



## IMPORTANT NOTICE

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